#### HIGH LINEARITY/DRIVER AMPLIFIER

### **RoHS Compliant & Pb-Free Product**

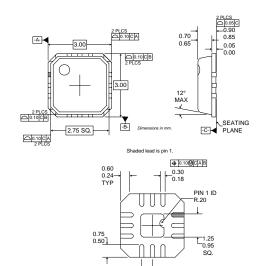
### Typical Applications

- Basestation Applications
- Cellular and PCS Systems
- CDMA, W-CDMA Systems

- GSM/EDGE Systems
- Final PA for Low-Power Applications

### **Product Description**

The RF3223 is a high-efficiency GaAs Heterojunction Bipolar Transistor (HBT) amplifier packaged in a low-cost surface-mount package. This amplifier is ideal for use in applications requiring high-linearity and low noise figure over the 500MHz to 3GHz frequency range. The RF3223 operates from a single 5V power supply, and is assembled in an economical 3mmx3mm QFN package.



Package Style: QFN, 12-Pin, 3x3

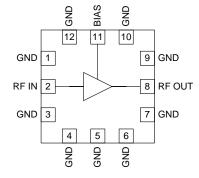
#### **Optimum Technology Matching® Applied**

- Si BJT **▼** GaAs HBT Si Bi-CMOS SiGe HBT
- GaAs MESFET ☐ Si CMOS

InGaP/HBT

GaN HEMT

SiGe Bi-CMOS



**Functional Block Diagram** 

#### **Features**

- 500MHz to 2000MHz
- +44.0dBm Output IP3
- +14.0dB Gain at 850MHz
- +11.4dBm Input P1dB at 850MHz
- 3.4dB Noise Figure at 850MHz
- Single 5V Power Supply

#### Ordering Information

RF3223 High Linearity/Driver Amplifier RF3223PCBA-41X Fully Assembled Evaluation Board

RF Micro Devices. Inc. Tel (336) 664 1233 7628 Thorndike Road Fax (336) 664 0454 Greensboro, NC 27409, USA http://www.rfmd.com

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### **Absolute Maximum Ratings**

<u> </u>					
Parameter	Rating	Unit			
RF Input Power	+20	dBm			
Device Voltage	-0.5 to +6.0	V			
Device Current	250	mA			
Operating Temperature	-40 to +85	°C			
Storage Temperature	-40 to +150	°C			



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Doromotor	Specification		Unit	Condition		
Parameter	Min.	Min. Typ. Max.		Unit	Condition	
Overall					V <sub>CC</sub> =5V, RF <sub>IN</sub> =-10dBm, Freq=850MHz, with Temp=25°C unless otherwise noted.	
AC Specifications					·	
Frequency	500		2000	MHz		
Gain (Small Signal)	12	14	15	dB		
Input VSWR		1.4	1.7	SWR		
Output VSWR		1.3		SWR		
Reverse Isolation	19	21				
Output IP3	41	45		dBm	$F_1 = 850 MHz, F_2 = 851 MHz$	
Output P1dB	23	+24.5		dBm		
Noise Figure		3.4	4.0	dB		
Thermal					I <sub>CC</sub> =160mA, P <sub>DISS</sub> =0.913W. (See Note)	
Theta <sub>JC</sub>		75		°C/W		
Maximum Measured Junction Temperature at DC Bias Con- ditions		154		°C	T <sub>CASE</sub> =+85°C	
Mean Time To Failures		5500		years	T <sub>CASE</sub> =+85°C	
DC Specifications						
Device Voltage	4.5	5.0	5.5	V	I <sub>CC</sub> =160 mA	
Operating Current Range	110	150	170	mA	V <sub>CC</sub> =5V	

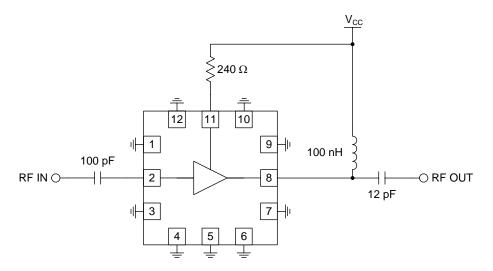
Note: The RF3223 must be operated at or below 175mA in order to achieve the thermal performance listed above. While the RF3223 may be operated at higher bias currents, 175mA is the recommended bias to ensure the highest possible reliability and electrical performance.

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Pin	Function	Description	Interface Schematic
1	GND	Ground connection.	
2	RF IN	RF input pin. This pin is not internally DC-blocked. A DC blocking capacitor suitable for the frequency of operation should be used.	To Bias Circuit RF IN ORF OUT
3	GND	Ground connection.	
4	GND	Ground connection.	
5	GND	Ground connection.	
6	GND	Ground connection.	
7	GND	Ground connection.	
8	RF OUT	Amplifier output pin. This pin is an open-collector output. It must be biased to $V_{CC}$ through a choke or matching inductor. This pin is typically matched to $50\Omega$ with a shunt bias/matching inductor and series blocking/matching capacitor. Refer to application schematics.	See pin 2.
9	GND	Ground connection.	
10	GND	Ground connection.	
11	BIAS	This pin is used to control the bias current. An external resistor may be used to set the bias current for any $V_{\text{PD}}$ voltage. Allows for trade-offs between IP3 versus noise figure and $T_{\text{MAX}}.$	>8—
12	GND	Ground connection.	
Pkg Base	GND	Ground connection. Vias to ground required under the package base.	

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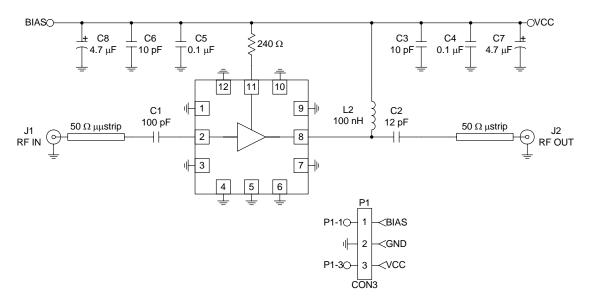
### **Application Schematic - 850MHz**



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### **Evaluation Board Schematic**

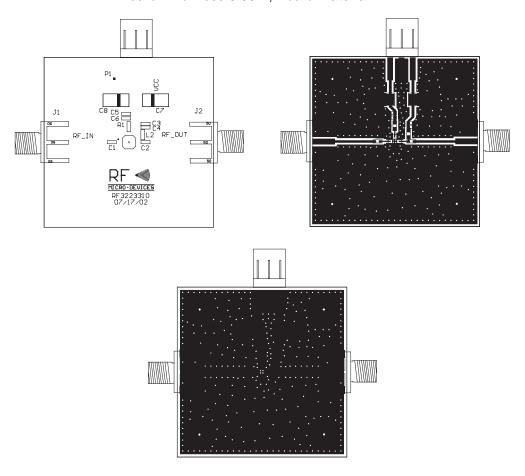
(Download Bill of Materials from www.rfmd.com.)



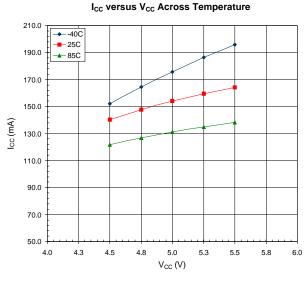
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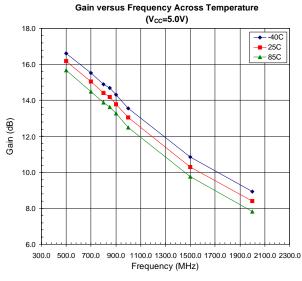
# Evaluation Board Layout Board Size 1.5" x 1.5"

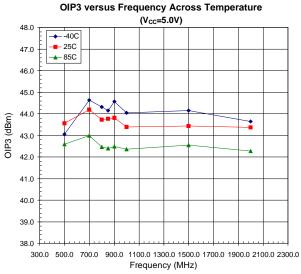
Board Thickness 0.032", Board Material FR-4

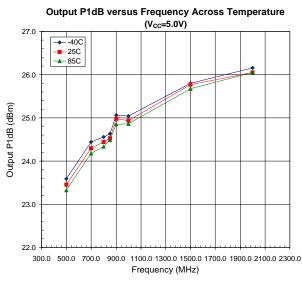


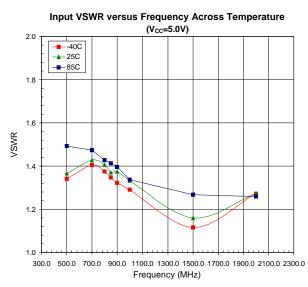
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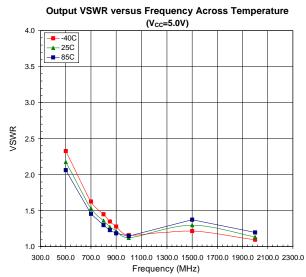




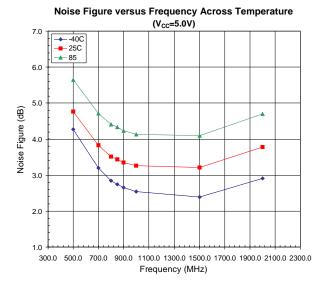








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